



# 125µm black low temperature reactive HAF mounting tape

# **Product Description**

tesa<sup>®</sup> Low Temperature Reactive (LTR) 58485 is a reactive mounting tape activated at moderate temperatures. This blackdouble sided tape has no backing. It is protected by a PE-coated paper liner.

tesa® LTR 58485 is free of halogen and compliant with current RoHS directive.

At room temperature tesa® LTR 58485 is not tacky. It is activated by moderate heat and pressure applied during the assembly process.

Special Features:

- \* Extremely high bonding performance and reliability, even on slim bonding areas and thin design gaps
- \* Activated at low temperature and pressure
- \* Excellent shock resistance
- \* Sebum resistant
- \* Very low oozing ratio

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### **Application Fields**

tesa® LTR 58485 is especially recommended for structural bonding of temperature sensitive substrates:

\* Bonding of anodized aluminium

For latest information on this product please visit http://l.tesa.com/?ip=58485





# **Application Fields**

\* Bonding of plastics

\* Mounting of sensitive electronic parts

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

# **Product Construction**

<ul><li>Backing</li><li>Type of adhesive</li><li>Type of liner</li></ul>	none low temperature activated reactive adhesive PE-coated paper	<ul><li>Total thickness</li><li>Color</li></ul>	125 μm black
Properties/Performance Values   • Bonding strength (push-out) 6.5 N/mm <sup>2</sup> • Low VOC very good			

### **Additional Information**

Technical recommendations:

tesa<sup>®</sup> LTR 58485 is not self adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

1. Pre-lamination:

During pre-lamination, laminate the adhesive tape onto the first component.

Setting:

\* Temperature<sup>1</sup> 50 – 60 °C

\* Pressure<sup>2</sup> 1 – 3 bar

For latest information on this product please visit http://l.tesa.com/?ip=58485





## **Additional Information**

\* Time 5 – 20 s

Short-time exposure to 60°C bond line temperature during pre-lamination does not impact final bonding potential.

2. Bonding:

Remove the liner from tape after the pre-lamination step.

Position the second component. Apply temperature and pressure for the bonding time to reach sufficient bonding strength.

Setting:

- \* Temperature<sup>1</sup> 75 110 °C
- \* Pressure<sup>2</sup> 2 4 bar
- \* Time 10 480 s

Short cycle times can be achieved at 110 °C bond line temperature. For activation at lower temperatures, increase the heat-press time or combine a short heat-press step with oven curing.

To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours.





# **Additional Information**

Bonding strength values were obtained under standard laboratory conditions (Material: PC/PC; bonding conditions: temperature (jig) = 90  $^{\circ}$ C; pressure = 5 bar; time = 120 sec).

Storage:

tesa recommends storage in original packaging in cool and dry conditions.

Low Temperature Reactive should not be exposed to more than 35°C before bonding (during transport, storage and converting).

The shelf life is 15 months after coating date. For the actual shelf life please refer to the best before date on the label in the log roll core.

<sup>1</sup> 'Pre-lamination' and 'Bonding' temperature refer to the data that is measured in the bond line.

<sup>2</sup> 'Pre-lamination' and 'Bonding' pressure refer to the force that is transferred from jig surface directly to the bonding area.

# Disclaimer

tesa<sup>®</sup> products prove their impressive quality day in, day out in demanding conditions and are regularly subjected to strict controls. All information and recommendations are provided to the best of our knowledge on the basis of our practical experience. Nevertheless tesa SE can make no warranties, express or implied, including, but not limited to any implied warranty of merchantability or fitness for a particular purpose. Therefore, the user is responsible for determining whether the tesa<sup>®</sup> product is fit for a particular purpose and suitable for the user's method of application. If you are in any doubt, our technical support staff will be glad to support you.



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